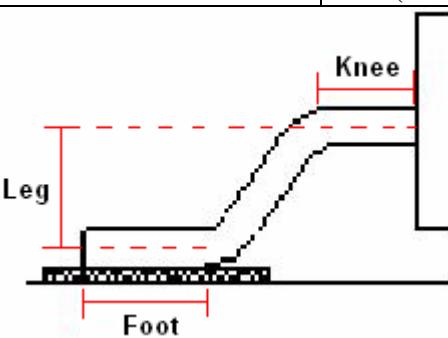


Package: QFN Sn

Feature	Value [mm] (in)
Package length Fig 3	5.0151 (0.1974)
Package width Fig 3	5.0151 (0.1974)
Package thickness	0.86 (0.0338)
Pitch Fig 6	0.65697 (0.0259)
Mass	0.06 g
CTE Strain Gauge Technique Temp range -50°C to 100°C Linear Correlation	8.361 ppm/°C (X - axis) 8.128 ppm/°C (Y- axis)
Die length Fig 5	N/A
Die width Fig 5	N/A
Die thickness Fig 5	0.2682 (0.0106)
Termination width Fig 6	0.24636 (0.0097)
Termination thickness Fig 6	0.2276 (0.0089)
Minimum Termination gap Fig 6	0.4107 (0.0162)
	
Termination length Fig 6	0.6269 (0.0247)
Lead leg length	N/A
Lead knee length	N/A

Feature	Value
Lead/Termination Base Metal Alloy	Cu 0.2276 Fig 5, 8 (0.0089)
Lead/Termination Metallization / thickness	Sn 9.268 [μm] Fig 7,10 (0.000365)
Plating 1 metallization / thickness	N/A
Plating 2 metallization / thickness	N/A
Plating 3 metallization / thickness	N/A
Over-plate to protect during cross section?	No
Diameter of solder balls	N/A
Solder ball alloy (SEM or XRF estimate)	N/A
Width of solder ball in contact w/ component pad	N/A
Width of component pad	N/A
Thickness of component pad	N/A
Diameter of solder mask opening	N/A

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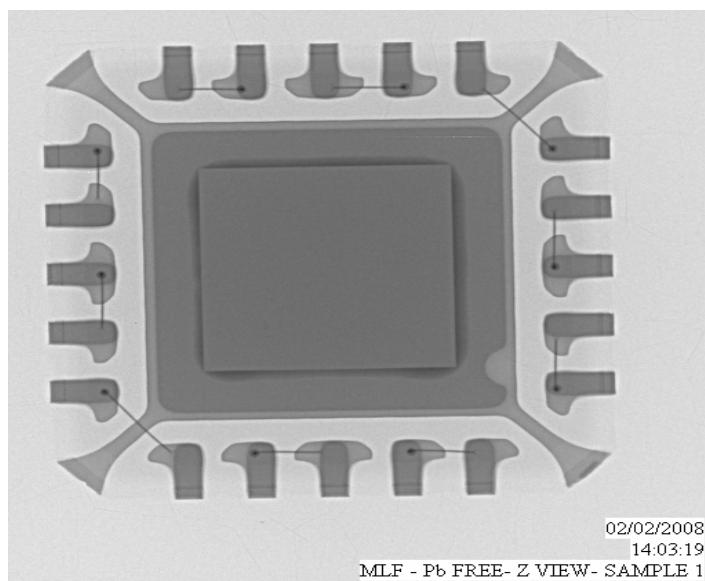


Fig.No.1 QFN Sn, X-ray, View Z

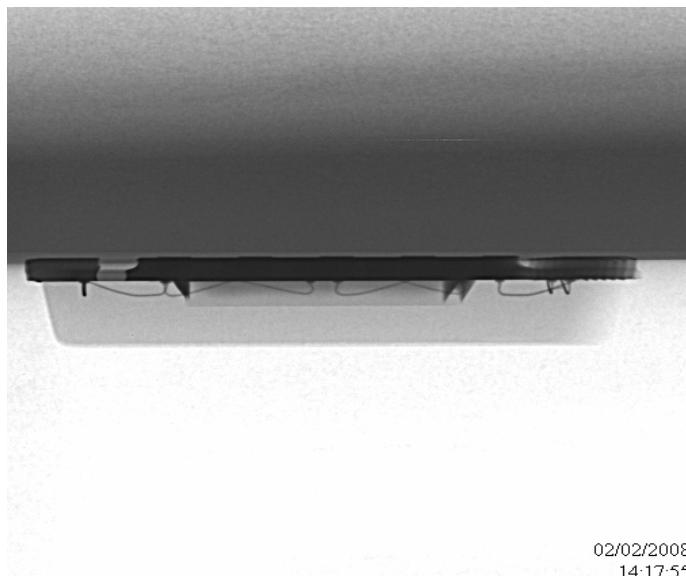


Fig.No.2 QFN Sn, X-ray, Inclined X-axis View

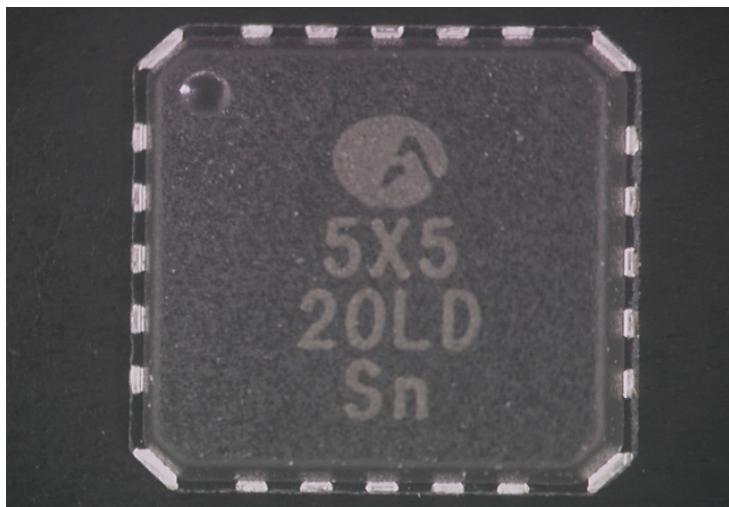


Fig No3. QFN Sn, Top View M~24X

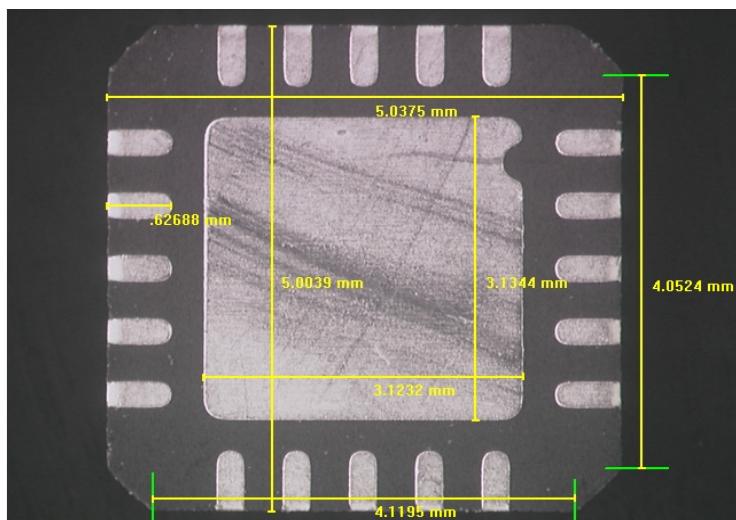


Fig No .4 QFN Sn, Bottom View M~24X

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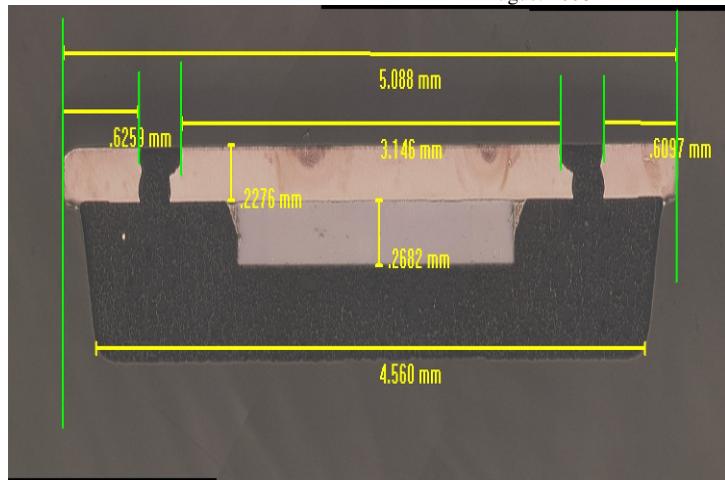


Fig No .5 QFN Sn, Cross section, M~64X

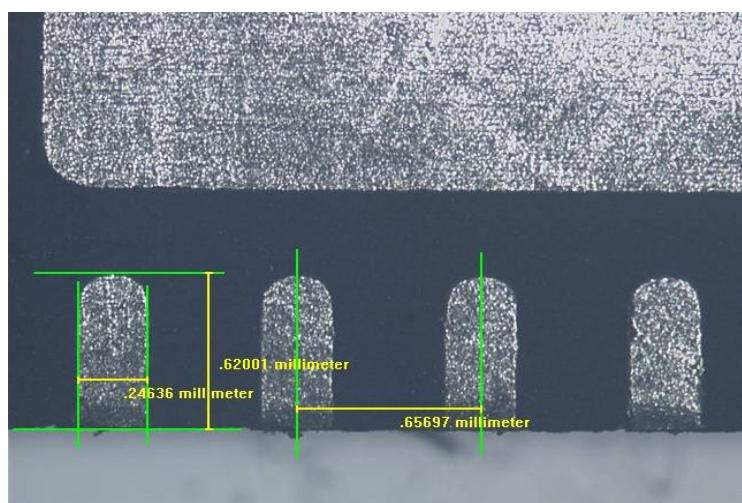


Fig No .6 QFN Sn, Bottom View M~64X

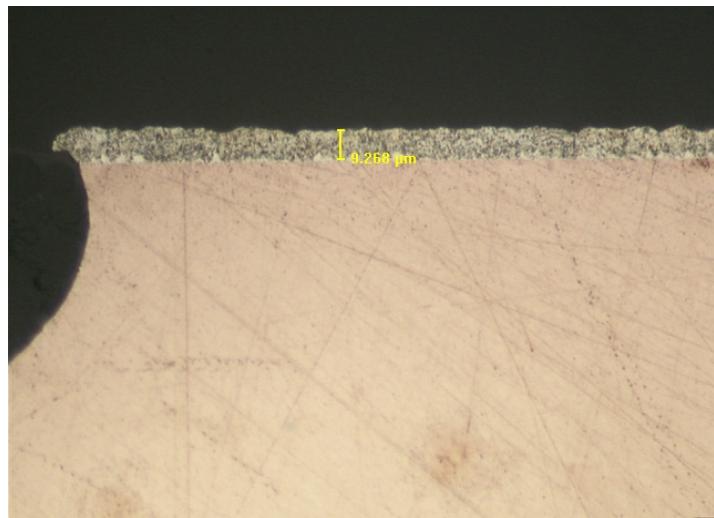
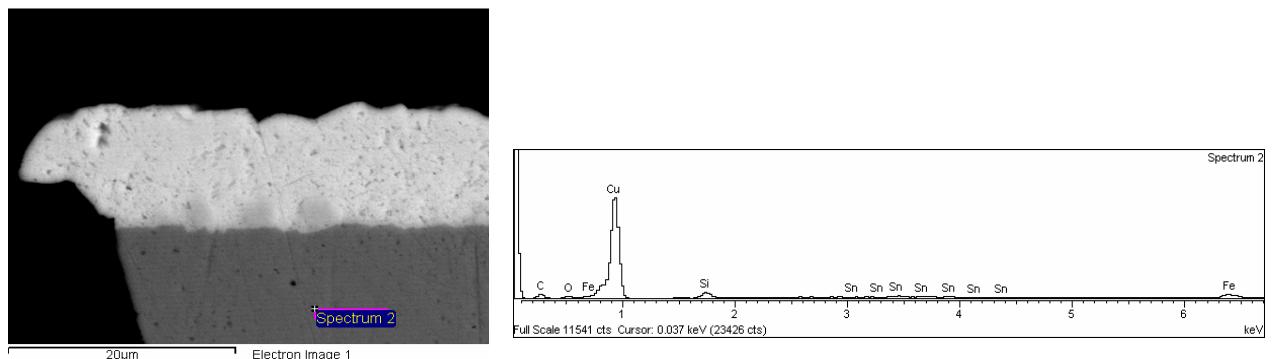


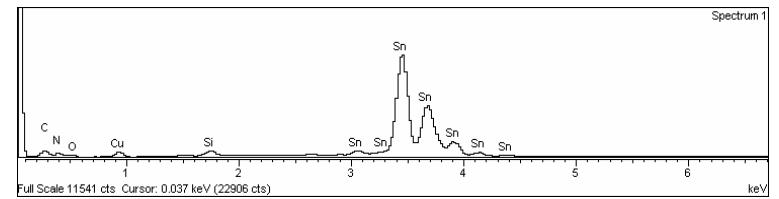
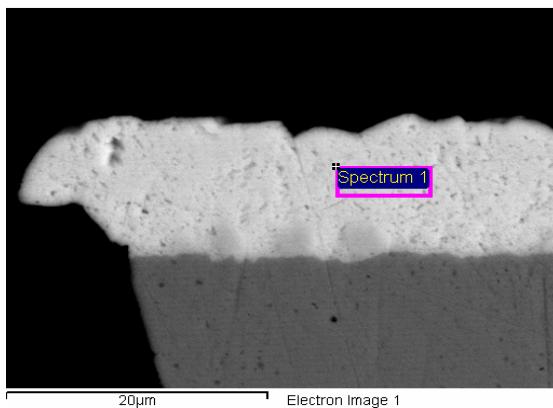
Fig No .7 QFN Sn, Cross section, Pad/Plating/Solder M~768X



Element	App Conc.	Intensity	Weight%	Weight%	Atomic%
	Conc.	Corrn.		Sigma	
C K	57.62	0.3076	21.15	0.91	55.40
O K	13.87	0.5562	2.82	0.38	5.54
Si K	8.59	0.3892	2.49	0.12	2.79
Fe K	14.85	1.1852	1.41	0.08	0.80
Cu K	585.33	0.9296	71.10	0.88	35.20
Sn L	7.71	0.8440	1.03	0.13	0.27
Totals			100.00		

Fig No .8 QFN Sn, Pad Material Analysis

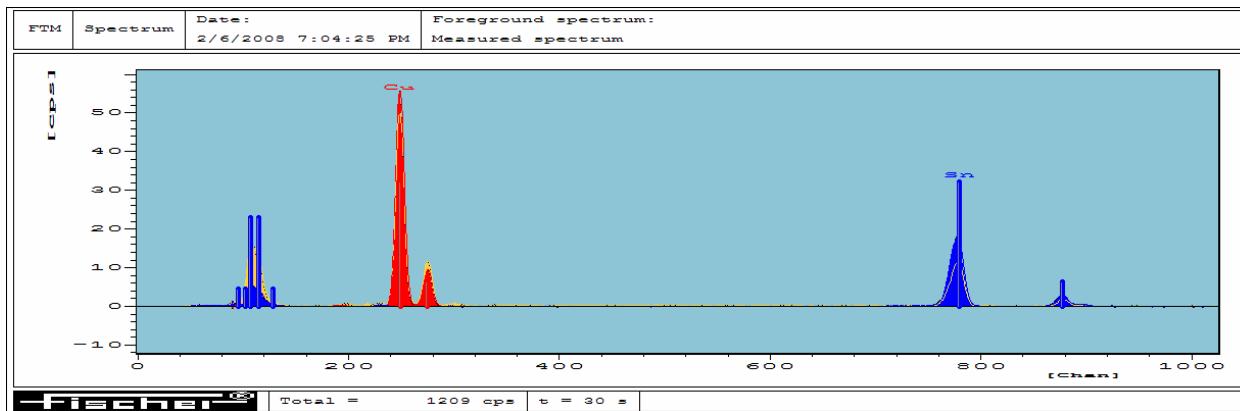
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Element	App	Intensity	Weight%	Weight%	Atomic%
	Conc.	Corrn.		Sigma	
C K	76.22	0.8858	10.83	0.60	38.51
N K	3.89	0.2961	1.66	1.93	5.05
O K	16.01	0.2163	9.32	1.08	24.86
Si K	7.28	0.5354	1.71	0.12	2.60
Cu K	33.96	0.9059	4.72	0.21	3.17
Sn L	543.57	0.9538	71.76	1.71	25.81
Totals			100.00		

Fig No .10 QFN Sn, Termination Metallization Top Layer Sn

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Foreground: Measured spectrum
Meas. para. (foreground spectrum):
High voltage = 50 kV (875) Prim. Filter = Ni
Collimator 3 = 0.60 Dm. Anode current 218 uA
Meas. distance = 0.003 inch

Results of analysis: (%)
29 Cu = 44.15
50 Sn = 55.85

Fig No .11 QFN Sn, Termination Metallization Top Layer Sn